

High Intensity SMD LED

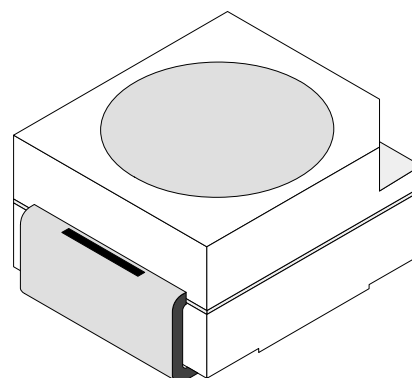
Color	Type	Technology	Angle of Half Intensity $\pm\varphi$
Double hetero red	TLMD3100	GaAlAs on GaAs	60°

Description

These new devices have been designed to meet the increasing demand for surface mounting technology. This device is used for outdoor or for low power applications.

The package of the TLMD310. is the PL-CC-2 (equivalent to a size B tantalum capacitor).

It consists of a lead frame which is surrounded with a white thermoplast. The reflector inside this package is filled up with clear epoxy.



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Features

- SMD LEDs with exceptional brightness
- Luminous intensity categorized
- Compatible with automatic placement equipment
- EIA and ICE standard package
- Compatible with infrared, vapor phase and wave solder processes according to CECC
- Available in 8 mm tape
- Low profile package
- Non-diffused lens: excellent for coupling to light pipes and backlighting
- Low power consumption
- Luminous intensity ratio in one packaging unit
 $I_{Vmax}/I_{Vmin} \leq 2.0$

Applications

Automotive: backlighting in dashboards and switches
 Telecommunication: indicator and backlighting in telephone and fax
 Indicator and backlight for audio and video equipment
 Indicator and backlight for battery driven equipment

Small indicator for outdoor applications
 Indicator and backlight in office equipment
 Flat backlight for LCDs, switches and symbols
 General use

Absolute Maximum Ratings

$T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified

TLMD3100

Parameter	Test Conditions	Type	Symbol	Value	Unit
Reverse voltage			V_R	6	V
DC forward current			I_F	30	mA
Surge forward current	$t_p \leq 10 \mu\text{s}$		I_{FSM}	0.5	A
Power dissipation	$T_{amb} \leq 60^{\circ}\text{C}$		P_V	100	mW
Junction temperature			T_j	100	$^{\circ}\text{C}$
Operating temperature range			T_{amb}	-40 to +100	$^{\circ}\text{C}$
Storage temperature range			T_{stg}	-55 to +100	$^{\circ}\text{C}$
Soldering temperature	$t \leq 5 \text{ s}$		T_{sd}	260	$^{\circ}\text{C}$
Thermal resistance junction/ambient	mounted on PC board (pad size $> 16 \text{ mm}^2$)		R_{thJA}	400	K/W

Optical and Electrical Characteristics

$T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified

Double hetero red (TLMD3100)

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Luminous intensity	$I_F = 10 \text{ mA}$		I_V	10	20		mcd
	$I_F = 1 \text{ mA}$		I_V		2		mcd
Dominant wavelength	$I_F = 10 \text{ mA}$		λ_d		648		nm
Peak wavelength	$I_F = 10 \text{ mA}$		λ_p		650		nm
Angle of half intensity	$I_F = 10 \text{ mA}$		ϕ		± 60		deg
Forward voltage	$I_F = 20 \text{ mA}$		V_F		1.8	2.2	V
Reverse voltage	$I_R = 10 \mu\text{A}$		V_R	6	15		V
Junction capacitance	$V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$		C_j		15		pF

Typical Characteristics ($T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified)

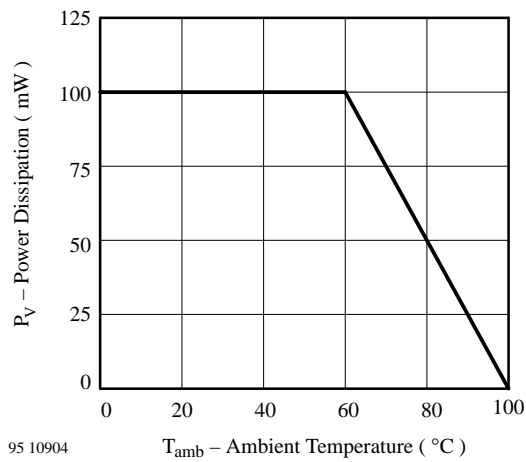


Figure 1. Power Dissipation vs. Ambient Temperature

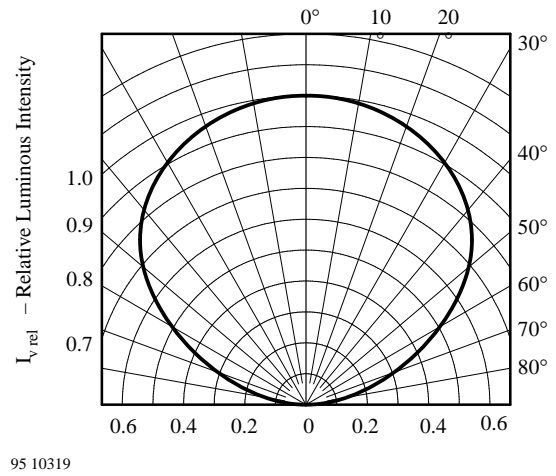


Figure 4. Rel. Luminous Intensity vs. Angular Displacement

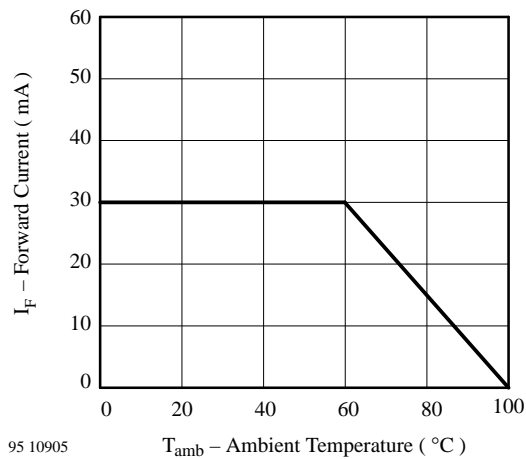


Figure 2. Forward Current vs. Ambient Temperature

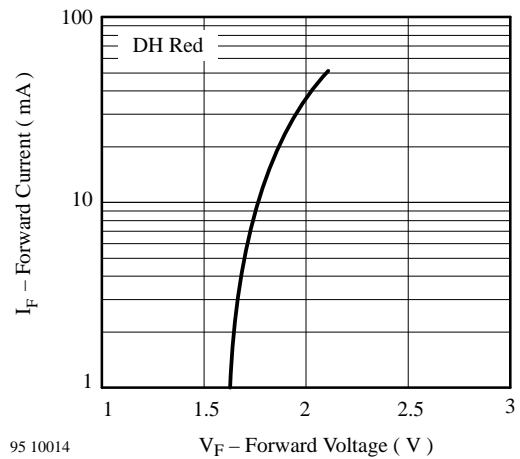


Figure 5. Forward Current vs. Forward Voltage

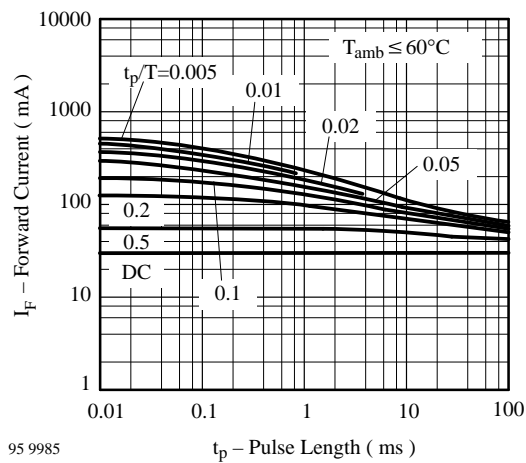


Figure 3. Forward Current vs. Pulse Length

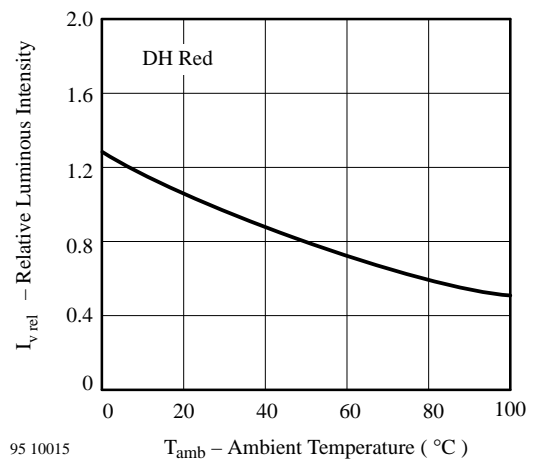


Figure 6. Rel. Luminous Intensity vs. Ambient Temperature

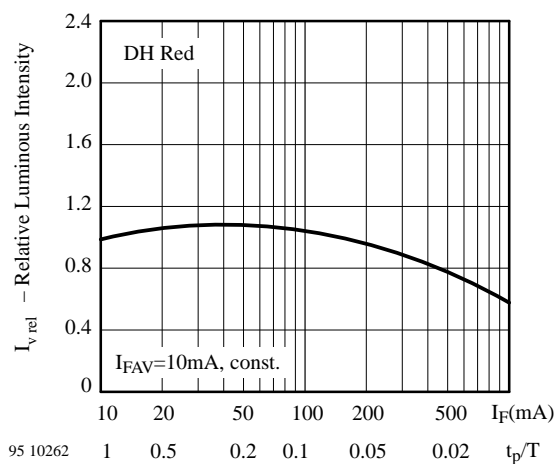


Figure 7. Rel. Lumin. Intensity vs. Forw. Current/Duty Cycle

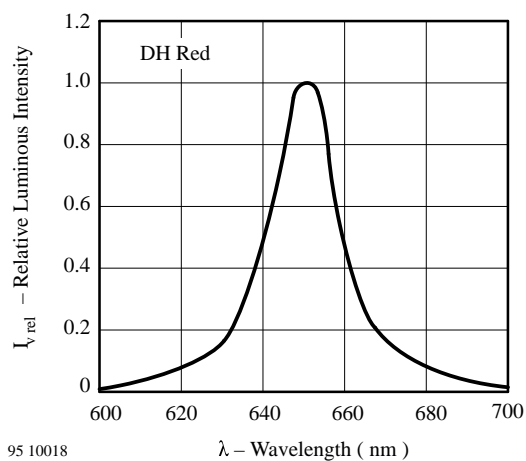


Figure 9. Relative Luminous Intensity vs. Wavelength

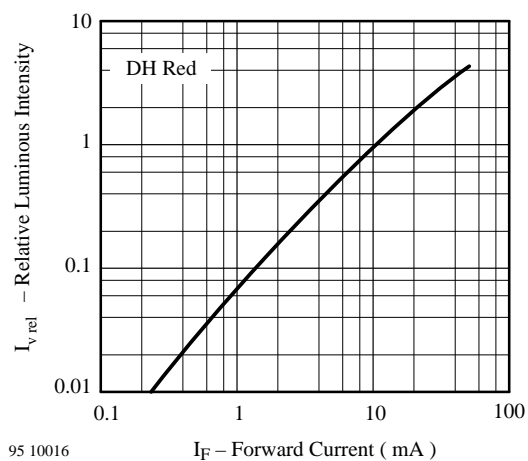
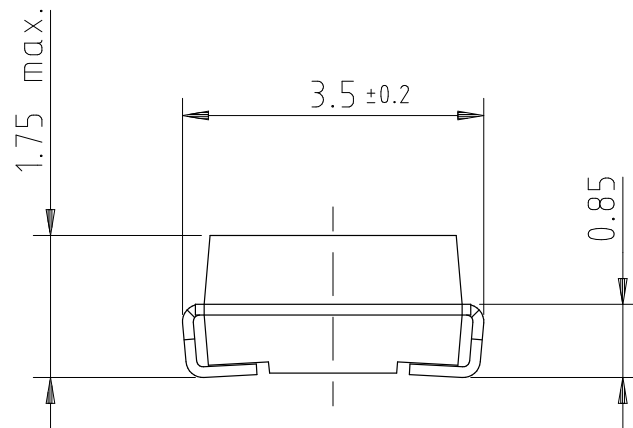
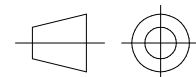
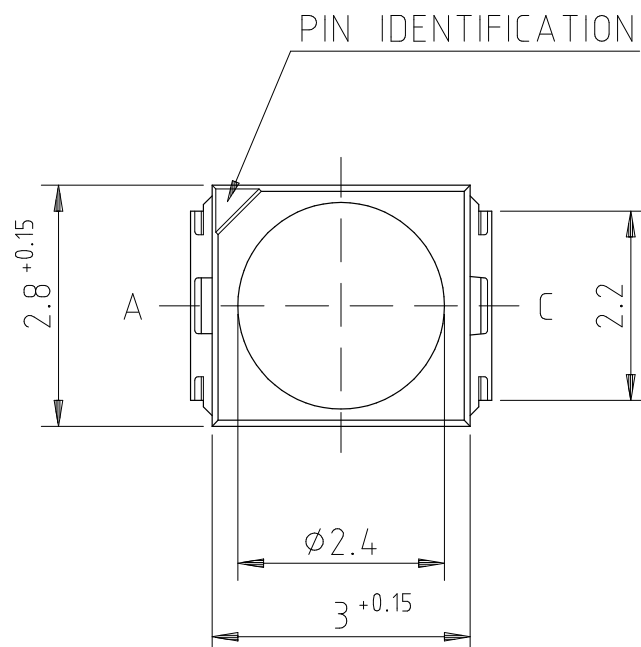


Figure 8. Relative Luminous Intensity vs. Forward Current

Dimensions in mm

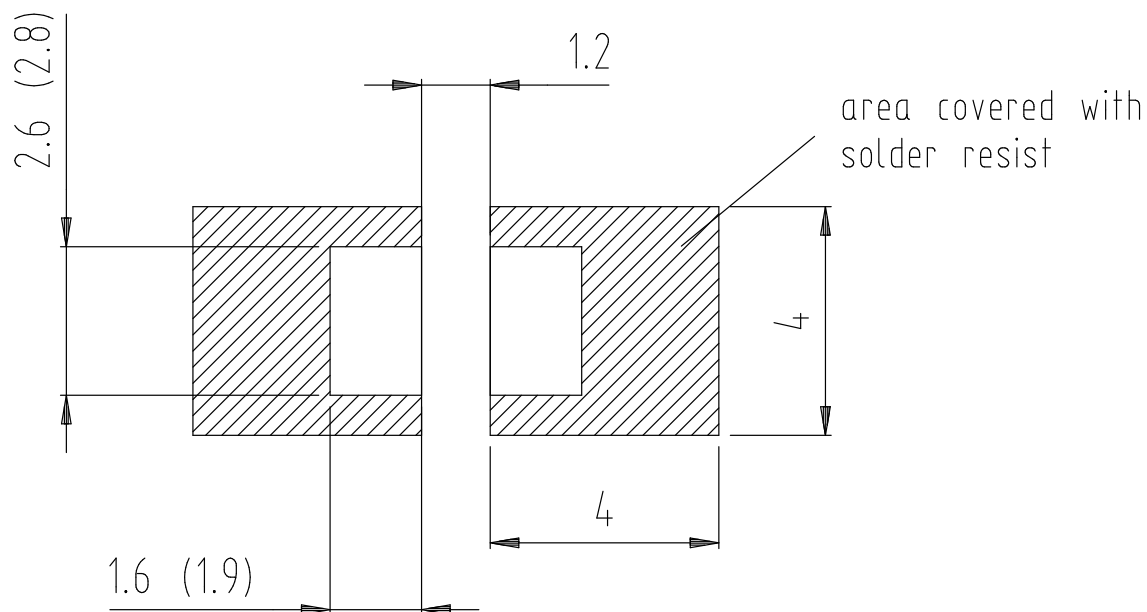


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technical drawings
according to DIN
specifications

PCB Layout in mm



Dimensions: IR and Vaporphase
(Wave Soldering)

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Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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